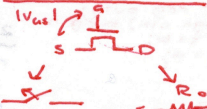


CMOS Transistors

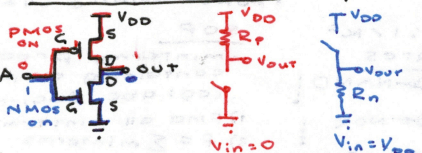
NMOS $V_{gs} < V_{th} \rightarrow$ Transistor OFF
 $V_{gs} > V_{th} \rightarrow$ NMOS on
 I proportional to V_{gs}

PMOS $V_{gs} > V_{th} \rightarrow$ on
 $V_{gs} < V_{th} \rightarrow$ off

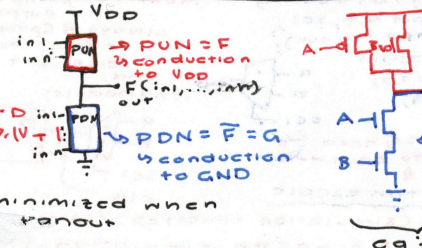
Symmetrical devices
 NMOS: drain at higher voltage
 PMOS: source at higher voltage



CMOS Inverter



PULL-UP & Down Networks



BASIC Circuitry

$$R = \frac{\rho L}{A W}$$

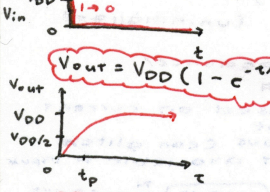
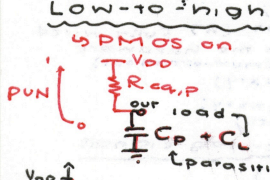
$$R_{series} = R_1 + R_2 + R_3 + \dots + R_N$$

$$R_{parallel} = R_1 || R_2 || \dots || R_N$$

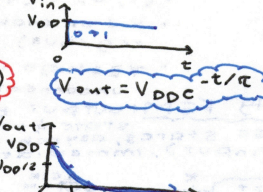
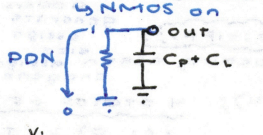
Inverter Delays



delay in inverter chains minimized when each stage has the same fanout



High-to-Low



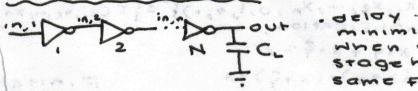
Capacitances

- C_{in} : input capacitance, largely set by C_g (gate capacitance) $C_g \sim WL$
- inverter: $C_{in,inv} = C_{g,pmos} + C_{g,nmos}$
- $W \rightarrow 2W \Rightarrow C_{in} \rightarrow 2C_{in}$
- C_p : parasitic capacitance, largely set by C_d (drain capacitance) $C_d \sim W$ (drain area/perimeter)
- inverter: $C_{p,inv} = C_{d,pmos} + C_{d,nmos}$
- $W \rightarrow 2W \Rightarrow 2C_p$
- $C_d = \gamma C_g$ ($\gamma = 1$)
- inverter: $C_p = \gamma C_{in}$

Inverter Sizing

- doubling W ($W \rightarrow 2W$)
- $C_{in} \rightarrow 2C_{in}$
- $C_p \rightarrow 2C_p$
- $R \rightarrow \frac{1}{2}R$
- $I \rightarrow 2I$

Inverter Chains

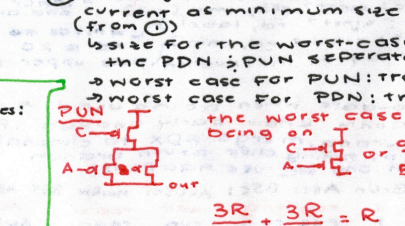


- delay minimized when each stage has same fanout
- Path Fanout (F)
$$F = \frac{C_L}{C_{in,i}} = \prod_{i=1}^N f_i$$
- Stage Fanout (f_i)
$$f_i = \sqrt[N]{F} = \sqrt[N]{C_L / C_{in,i}}$$

LOGICAL EFFORT

How to calculate

- Draw equivalent inverter inverter with the same resistance
- Find $R_{eq,inv}$, $C_{in,inv}$
- Size gate to have same output current at minimum size inverter (from 1)



- Minimum path delay (D)
$$D = N \sqrt[N]{F} + N = N(P + \sqrt[N]{F})$$
- size of each inverter stage ($C_{in,i}$)
- overall (not min) path delay (D)
$$D = \sum (1 + f_i) = N + \sum f_i$$

$\tau_p = \ln(2) \tau = 0.7 \tau$

$\tau_p = \ln(2) R_{eq} (\gamma C_{in} + C_L) = \ln(2) R_{eq} C_{in} (\gamma + C_L / C_{in})$

$\tau_{inv} = \ln(2) R_{eq} C_{in}$ (indep of transistor sizes)

Normalized Delay to τ_{inv} effort delay

$$D(inv) = \tau_p / \tau_{inv} = 1 + F$$

inverter delay: $\tau_{p,inv} = \gamma + FO$

Branch Effort

delay expression: $\sum_{i=1}^N \tau_{inv}(C_{p,i} + \theta_i f_i)$

Assume $\tau_{inv} = 10ps$, $\gamma = 1$, $R_{eq,inv} = R_{eq}$. Find optimal x, y, z to minimize delay.

Take partial derivatives of delay, set equal to 0 & solve

$$\frac{\partial \tau_{delay}}{\partial x} = 1 - \frac{9y}{2x^2} = 0, \quad \frac{\partial \tau_{delay}}{\partial y} = \frac{9}{2x} - \frac{3+10}{y^2} = 0$$

Solve system: $x = 8.55, y = 16.25, z = 129.01$

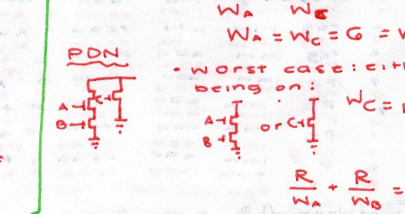
Branch Factor b_i : $b_i = \frac{Z_{on} + Z_{off}}{Z_{on,parh}}$

Stage Effort of Stage i (SE_i): $SE_i = b_i f_i (LE_i)$

Logical Effort (LE_i): $LE_i = \frac{C_{in,gate}}{C_{in,inv}}$

Multi-Stage Networks

- Delay = $\sum_{i=1}^N (P_i + LE_i * FO_i)$
- stage effort: $SE_i = LE_i * FO_i$
- Path Fanout Effort: $FO_{path} = C_{load} / C_{in}$
- Path logical effort: $LE_{path} = LE_1 * LE_2 * \dots * LE_N$
- Path Effort: $PE = LE_{path} * FO_{path}$
- Best stage effort: $\sqrt[N]{PE} = SE_{opt}$
- minimum path delay: $N * SE_{opt} + P$
- best effective fanout of each stage: $FO_i = \frac{SE_{opt}}{LE_i}$



Logical Effort (LE_{gate}): $LE_{gate} = \frac{R_{eq,gate}}{R_{eq,inv}} \cdot \frac{C_{in,gate}}{C_{in,inv}}$

if you size the gate to have same resistance as the inverter, simplifies to

$$LE_{gate} = \frac{C_{in,gate}}{C_{in,inv}}$$

- Find $R_{eq,inv}$, $C_{in,inv}$
- Size gate to have same output current at minimum size inverter (from 1)

Total D ($\tau_{p,tot}$)

$$\tau_{p,tot} = \tau_{p,inv} + \tau_{inv}(P + \sqrt[N]{F}) + \tau_{inv}(P_{gate})$$

Gate sizing example

$$LE_1 = 1, LE_2 = \frac{3}{2}, LE_3 = \frac{3}{2}, LE_4 = \frac{3}{2}$$

$$FO_1 = \frac{3}{2}, FO_2 = \frac{3}{2}, FO_3 = \frac{3}{2}, FO_4 = \frac{3}{2}$$

$$PE = LE_1 * FO_1 = 1 * \frac{3}{2} = 1.5$$

$$SE_{opt} = \sqrt[4]{1.5} = 1.1$$

$$D = N * SE_{opt} + P = 4 * 1.1 + 1 = 5.4$$

$$C_{in} = LE * \frac{C_{out}}{SE_{opt}}$$

$$f_2 = 1 * \frac{3C}{3} = C, \quad f_3 = \frac{3}{2} * \frac{3}{3} = \frac{3}{2}, \quad f_4 = \frac{3}{2} * \frac{3}{3} = \frac{3}{2}$$

$$x = \frac{3}{2} * \frac{3}{3} = \frac{3}{2} = 1.5$$

Worst case for PUN: transistors in series

Worst case for PDN: transistors in parallel

the worst case is either A or B being on

$$\frac{3R}{W_A} + \frac{3R}{W_B} = R$$

$$W_A = W_B = G = W_B \text{ (wlog)}$$

Worst case: either A & B or C being on

$$\frac{R}{W_A} + \frac{R}{W_B} = R$$

$$W_A = W_B = 2$$

Gate sizing example

$$LE_1 = 1, LE_2 = \frac{3}{2}, LE_3 = \frac{3}{2}, LE_4 = \frac{3}{2}$$

$$FO_1 = \frac{3}{2}, FO_2 = \frac{3}{2}, FO_3 = \frac{3}{2}, FO_4 = \frac{3}{2}$$

$$PE = LE_1 * FO_1 = 1 * \frac{3}{2} = 1.5$$

$$SE_{opt} = \sqrt[4]{1.5} = 1.1$$

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$$C_{in} = LE * \frac{C_{out}}{SE_{opt}}$$

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$$x = \frac{3}{2} * \frac{3}{3} = \frac{3}{2} = 1.5$$

Gate sizing example

$$LE_1 = 1, LE_2 = \frac{3}{2}, LE_3 = \frac{3}{2}, LE_4 = \frac{3}{2}$$

$$FO_1 = \frac{3}{2}, FO_2 = \frac{3}{2}, FO_3 = \frac{3}{2}, FO_4 = \frac{3}{2}$$

$$PE = LE_1 * FO_1 = 1 * \frac{3}{2} = 1.5$$

$$SE_{opt} = \sqrt[4]{1.5} = 1.1$$

$$D = N * SE_{opt} + P = 4 * 1.1 + 1 = 5.4$$

$$C_{in} = LE * \frac{C_{out}}{SE_{opt}}$$

$$f_2 = 1 * \frac{3C}{3} = C, \quad f_3 = \frac{3}{2} * \frac{3}{3} = \frac{3}{2}, \quad f_4 = \frac{3}{2} * \frac{3}{3} = \frac{3}{2}$$

$$x = \frac{3}{2} * \frac{3}{3} = \frac{3}{2} = 1.5$$

Dennard Scaling

- device dim (box, L, W),
- doping concentration (Na): K
- power dissipation per circuit (VZ): 1/K²
- power/performance
- Power P = 1/2 CV²f
- Performance (f)
- Power density = VI/A

current, voltage, capacitance (eA/E), delay time per circuit (VC/I) : 1/K
 • power density (VI/A) : 1

Boolean Algebra

DeMorgan's Law:

$$\overline{x+y} = \overline{x} \cdot \overline{y}$$

$$\overline{x \cdot y} = \overline{x} + \overline{y}$$

Identities

$$x + 0 = x$$

$$x + 1 = 1$$

$$x \cdot 1 = x$$

$$x \cdot 0 = 0$$

Idempotence: x+x=x, x*x=x

Complements: x+x̄=1, x*x̄=0

Commutative:

$$x+y = y+x$$

$$x \cdot y = y \cdot x$$

Associative: x+(y+z) = (x+y)+z

Distributive:

$$x \cdot (y+z) = x \cdot y + x \cdot z$$

Absorptive:

$$x + x \cdot y = x$$

$$x \cdot (x+y) = x$$

$$x \cdot (x+y) = (x \cdot x) + (x \cdot y) = x + (x \cdot y) = x$$

Simplification:

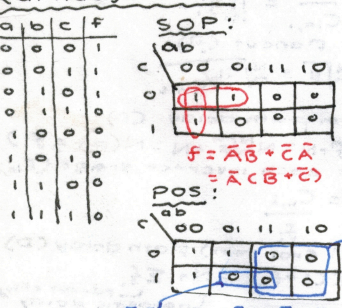
$$x \cdot y + x \cdot \overline{y} = x$$

$$(x+y) \cdot (x+\overline{y}) = x$$

$$x \cdot (x+y) = x$$

$$x + x \cdot y = x$$

Karnaugh maps

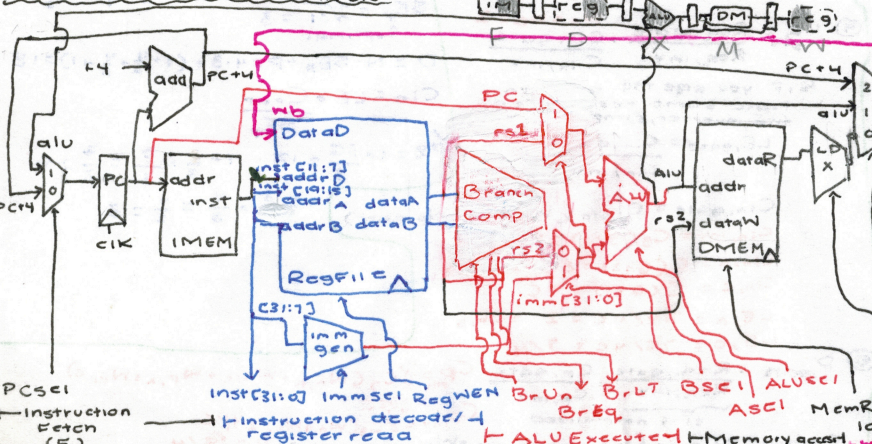


RISC-V Hazards

- Structural - 1 resource required by >1 instruction
 - data: 1+ src register(s) not up-to-date when being used
 - control: for branch instructions, don't know early enough if branch is taken
- Control hazards (because caused by timing diff b/w branch control logic truth table comparison and PC update happens)

inst [31:0]	BrEq	BrLT	PCsel	ImmSel	BrUn	Asel	BSel	ALUSel	MemRW	REV	WB
add	+	+	+	+	+	+	+	+	+	+	+
and	+	+	+	+	+	+	+	+	+	+	+
or	+	+	+	+	+	+	+	+	+	+	+
sub	+	+	+	+	+	+	+	+	+	+	+
sw	+	+	+	+	+	+	+	+	+	+	+
ld	+	+	+	+	+	+	+	+	+	+	+
sd	+	+	+	+	+	+	+	+	+	+	+
beq	+	+	+	+	+	+	+	+	+	+	+
bne	+	+	+	+	+	+	+	+	+	+	+
blt	+	+	+	+	+	+	+	+	+	+	+
bltu	+	+	+	+	+	+	+	+	+	+	+
jalr	+	+	+	+	+	+	+	+	+	+	+
jal	+	+	+	+	+	+	+	+	+	+	+
auipc	+	+	+	+	+	+	+	+	+	+	+

RISCV Datapath With Controls



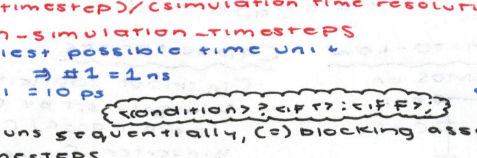
SOP

- minterms: product terms containing all input combos (eg: abc, abc̄, ...) (output=1)
- 1) Find all minterms where output=1
- 2) f = Σ minterms

Behavioral/sequential (synchronous)/nonblocking

```

module seq(input a, b, sel, clk);
    output reg out;
    always @ (posedge clk) begin
        if (sel) out = b;
        else out = a;
    end;
endmodule;
    
```



POS

- maxterm: sum terms involving all input combos (eg: a+b+c), (ā+b+c, ...)
- 1) Find all maxterms
- 2) F = Σ maxterms
- 3) F = Σ maxterms

2D regs/memory

```

reg [31:0] mem [7:0];
// 8 elements
mem [2]; // 3rd 32-bit element
mem [5][7:0]; // 6th element's lowest byte (8b)
    
```

Generate loops

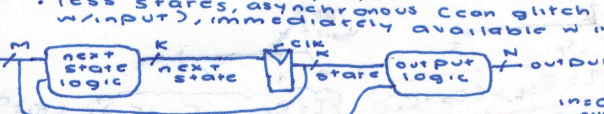
```

generate
    for (i=0; i<n; i++) begin
        generate_for (j=0; j<n; j++) begin
            assign z[i][j] = x[i][j];
        end
    end
endgenerate;
    
```

4 states of Verilog signals

- (1, 0) = (T, F)
- x = unknown (uninitialized reg/bus)
- z = high impedance/unconnected

Meady FSM: output based on current state & input



Mealy edge detector:

input	curr state	next state	output
0	zero	zero	0
1	zero	one	1
0	one	zero	0
1	one	one	0

- For FSMs, in general, we have 2 main sections in Verilog code
- 1) state transition: sequential
- 2) state/output logic: combinational

RISC-V control signals

- INPUTS:
 - instruction - read from instr mem
 - BrEq: 1 if inputs to branch comparator are equal
 - BrLT: 1 if input1 < input2
- OUTPUTS:
 - PCsel: 0 ALU output, 1 PC+4
 - ImmSel: 1 of 5 type based on imm type
 - RegWEN: 1 Enable writeback to register file
 - BrUn: 1 unsigned branch comp. mode
 - ASel: selects ALU input 1 to be 1 PC or rs1
 - BSel: selects ALU input 2 to be 1 immediate or rs2
 - ALUSel: select 1 of 10 operations
 - MemRW: write to memory
 - WBSEL: write data from 2 PC+4 (ALU or Data Memory) to rd

Pseudoinstruction

```

breq rs1 label
breq rs1 x0 label
bneq rs1 label
bneq rs1 x0 label
jalr x0 label
jalr x0 rs1
jalr x0 rs1 0
jalr x0 x0
jalr x0 x0 0
    
```

```

mv rd rs1
baddi rd rs1 0
neg rd rs1
bsub rd x0 rs1
nop
baddi x0 x0 0
wxor rd rs1 -1
rct (PC=ra)
bjair x0 x1 0
    
```

Single-cycle Datapath Equations

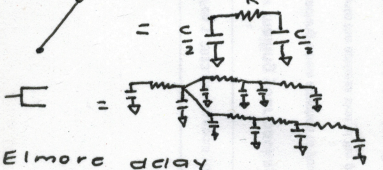
- critical path / clk cycle / clk period:
 - largest combinational block
 - increase clk f by pipelining
 - total stall cycles: (Bmisred) (Bout)
 - stall cycle for branch misprediction is 3 cycles
 - be while walking if the branch is taken or not at the x stage, the target addr is computed at the M stage
- min clk cycle: MEMRW
- max clk freq: f = 1/min_cyc
- throughput = (#operations) / time
- latency = (#stages in DP) * (t_clk)

Branching

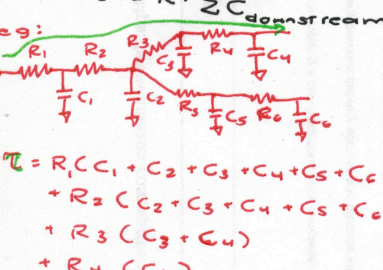
- branch factor $b_i = \frac{\sum_{on-path} + \sum_{off-path}}{\sum_{on-path}}$
- Path branching effort: $B = \Pi b_i$
- Path Effort: $PE = B \cdot FO_{path} \cdot LE_{path} = B \left(\frac{C_{out}}{C_{in}} \right) (\Pi LE_i)$
- Best stage effort $SE_{opt} = \sqrt[N]{PE} = b_i \cdot FO_i \cdot LE_i$
- Path delay $D = N \cdot SE_{opt} \cdot \tau$

Elmore Delay

wire RC model (π model)



Elmore delay
 → start at $\tau = 0$
 → τ at each resistor,
 $\tau = R \cdot \sum C_{downstream}$



$\tau = R_1(C_1 + C_2 + C_3 + C_4 + C_5 + C_6) + R_2(C_2 + C_3 + C_4 + C_5 + C_6) + R_3(C_3 + C_4) + R_4(C_4)$

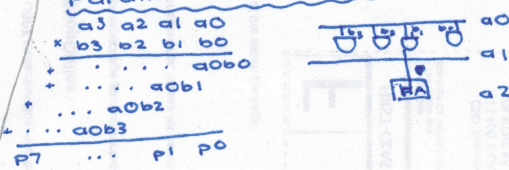
Energy

$E_c = \int_0^{\infty} I(t)V(t)dt = \int_0^{\infty} C \frac{dV(t)}{dt} V(t) dt$
 $= C \int_0^{V_0} V(t) dV = \frac{1}{2} CV_0^2 \leftarrow \text{Energy}$
 $P_c = \frac{E_c}{T} = \frac{1}{2} CV_0^2 f \leftarrow \text{Power (Watts)}$
 $C = \frac{\epsilon L W}{d} \leftarrow \text{capacitance}$

to achieve lowest power design for the minimum delay, additional inverters/buffers should be placed right before the load capacitor
 dynamic power = $P_{dynamic} = \alpha C V_{DD}^2 f$
 switching power - when both transistors are on ($V_{DD} - V_{thp} > V > V_{thn}$), i.e. when it's switching from on to off or vice versa $P_{switching} = IV = V^2/R$
 leakage power (when $R_{off} \ll \infty$)

Multippliers

Parallel Array Multiplier



Booth Recoding

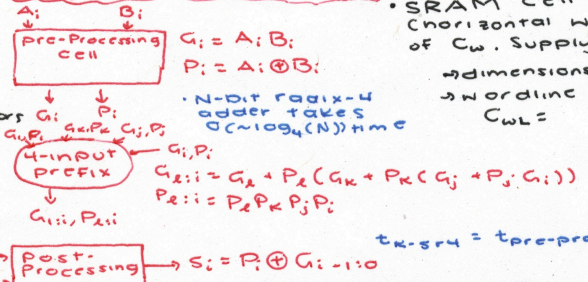
$(B_{k+1}, B_k)(A) = 0A \rightarrow 0$
 $= 1A \rightarrow A$
 $= 2A \rightarrow 4A - 2A$
 $= 3A \rightarrow 4A - A$

B_{k+1}	B_k	action
0	0	0
0	0	0
0	1	+1
0	1	+
1	0	-2
1	0	-
1	1	-1
1	1	0

$\begin{array}{r} \times 0111 \\ 1010 \\ \hline 01110 \end{array}$

Energy per instruction:
 $E_{instr} = P_c \cdot t_{inst}$
 $= P_c (CPI \cdot \frac{1}{f})$
 Energy for n instr:
 $E_n = n \cdot E_{instr}$
 Energy delay prod. for n instructions:
 $EDP = n \cdot E_n (CPI) (\frac{1}{f})$

Kogge-Stone Cradix 4 adder

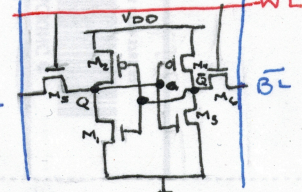


Flip Flops

Timing

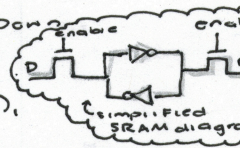
- minimum cycle time set by longest 10 path:
 $T > t_{clk-to-q} + t_{logic,max} + t_{setup}$
- setup slack = $T - (t_{clk-to-q} + t_{logic,max} + t_{setup})$
- hold time constraint:
 $t_{hold} < t_{clk-q} + t_{logic,min}$
- hold slack = $t_{clk-q} + t_{logic,min} - t_{hold}$
- when we have jitter t_j , skew:
 - minimum cycle time:
 $T > t_{c-q} + t_{logic,max} + t_{su} - t_{sk} + t_j$
 - hold time constraint:
 $t_{hold} + t_{sk} + t_j < t_{c-q} + t_{logic,min}$
 - hold slack:
 $t_{clk-to-q} + t_{logic,min} - (t_{hold} + t_{skew})$
 - setup slack:
 $T - (t_{clk-q} + t_{logic,max} + t_{setup}) + t_{skew}$

SRAM Cell



- write: $BL \uparrow, \overline{BL} \text{ are inverted}$
- read: $BL \uparrow, \overline{BL} \text{ are not inverted}$
- wordline enables read/write access for a row
- GT SRAM can only support 1 read/1 write port

sizing: $(\frac{W}{L})_2 : (\frac{W}{L})_5 : (\frac{W}{L})_1$



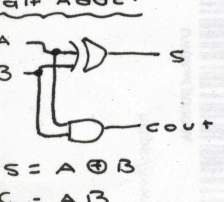
- writeability: $(\frac{W}{L})_2 < (\frac{W}{L})_5$ necessary
- read stability: $(\frac{W}{L})_5 < (\frac{W}{L})_1$ necessary
- the bitline that is pulled low is the one involved in flipping the cell state during a write operation
- GT SRAM techniques like adjusting voltages of wordlines, bit lines, or the latch pair that improve read stability, hurt writeability because they're coupled together (unlike 6T cells)
- SRAM cell leakage degrades read access over time

Memory Implementation

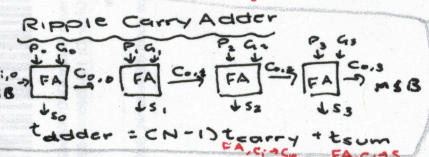
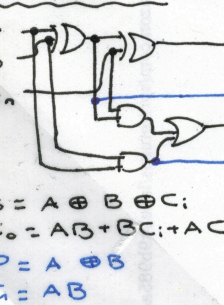
SRAM cell: height $h_{\mu m}$, width $w_{\mu m}$
 (horizontal WL, vertical BL), wire capacitance of C_w . Supply voltage of V_s . Has n rows, m columns
 → dimensions: (n rows) $(h_{\mu m})$
 → wordline capacitance:
 C_{wL}

$t_{k-sr4} = t_{pre-processing} + 2t_{prefix} + t_{post-processing}$

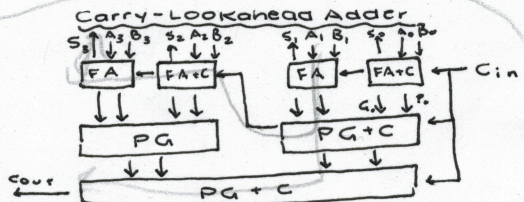
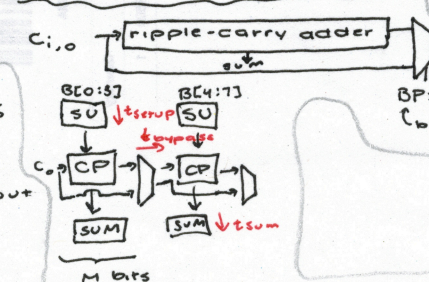
Half Adder



Full Adder



Carry-bypass/skip adder



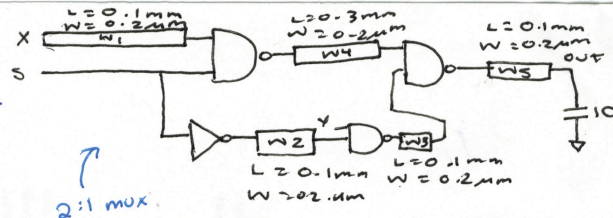
$C_0 = AB + BC_i + A_i C_i = G + P C_i$
 $P = P_1 P_2 P_3 \dots P_N$
 $G = G_1 + P_1 G_2 + P_1 P_2 G_3 + \dots + (P_1 P_2 \dots P_{N-1}) G_N$
 $C_{out,k} = G_k + P_k C_{out,k-1}$

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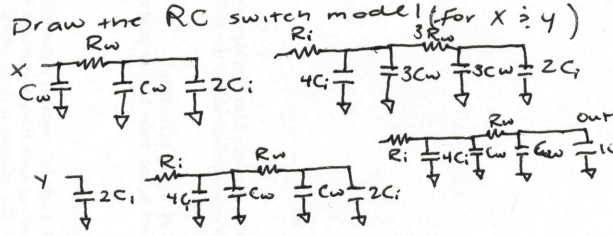
Find minimum unsigned entry in an asynch read RAM by iterating through one entry per clk cycle.
reg [7:0] ram [0:15];
reg [4:0] addr; // (2^4 = 16 = entries in ram)
reg [7:0] minimum; // each ram entry is 8 bits wide
always @(posedge clk) begin
  if (rst)
    addr <= 0;
  else
    addr <= addr + 1;
end
always @(posedge clk) begin
  if (rst)
    minimum <= ram[0];
  else
    minimum <= (ram[addr] < minimum) ? ram[addr] : minimum;
end

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if the regfile is asynch read, synch write, we can remove the explicit registers b/w the mem access & WB stages & maintain the same functionality
 For B-format instr. if we assume branch always taken, we need extra hardware in the F stage to calculate the new address



- W_1 has resistance R_w & parasitic capacitance $2C_w$
- inverters have input cap C_i , parasitic cap $2C_i$; output res R_i
- NAND - input $2C_i$, parasitic $4C_i$, output R_i

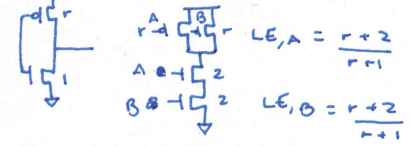


cycle ALU. 2 N-bit inputs, M distinct operations, you can simulate the ALU at a speed of $C Hz$ (C clk cycle / sec). How long does it take to exhaustively test the ALU? $(2^N \cdot 2^M) / C$ seconds
 Behavioral description of a decoder
 wire [25:10] dec;
 assign dec = 25'd1 << addr;

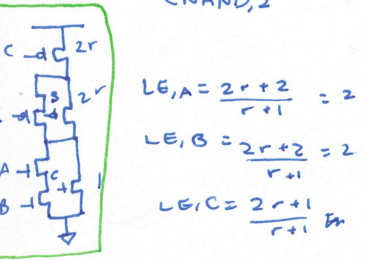
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1 bit decoder logic
wire [25:10] dec;
assign dec[0] = !addr;
assign dec[1] = addr;

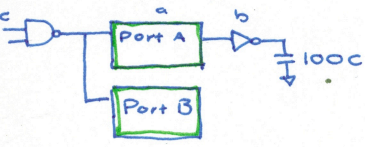
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LE_A = $\frac{r+2}{r+1}$
 LE_B = $\frac{r+2}{r+1}$



LE_A = $\frac{2r+2}{r+1} = 2$
 LE_B = $\frac{2r+2}{r+1} = 2$
 LE_C = $\frac{2r+1}{r+1}$



$P_f = FO_{path} \cdot B \cdot LE_{path} = (100)(2)(\frac{r+2}{r+1} \cdot 2 \cdot 1) = 400(\frac{r+2}{r+1})$

Propagation delay from input to output?
 $t_p = \ln 2 (R_1 C_1 + \dots + R_N C_N) = (\ln 2)(27RC)$

Suppose you can add as many buffers to the path to minimize path delay. How many should you add?

Previously:
 $PE = 2IG$ Path Delay = 24 P = G N = 3
 Now: $D = N \sqrt{PE/P} + P = N \sqrt{2IG/G} + G \cdot 2x$
 $\# \text{ buffers} = 0 \rightarrow N = 3$ D = 24
 $\rightarrow 1 \rightarrow N = 5$ D = $5 \sqrt{2IG} + G + 2 \approx 22.65$
 $\rightarrow 2 \rightarrow N = 7$ D = $7 \sqrt{2IG} + G + 4 = 25.09$
 bc 2 inverters
 add 1 buffer
 place it before the largest load C

Physical Array Organization

SRAM Array. 1024 entries of 8 bits. Each cell is 0.12um high & 0.5um wide (where WL horizontal, BL vertical). Wire capacitance of 0.2 fF/um & supply voltage of 0.9V.
 if you build an array of 1024 rows & 8 columns, how much energy is used to drive the WL?
 $E_{wl} = C_{wl} \cdot V^2 = (8 \text{ cells} \cdot \frac{0.5 \mu m}{1 \text{ cell}} \cdot \frac{0.2 \text{ fF}}{1 \mu m}) (0.9 \text{ V})^2 = 0.65 \text{ fJ}$
 (one WL turns on)
 if you build the same array as in part (a), how much energy is discharged from the Bitlines (assuming the WL is left on for a long time)?
 $E_{bl} = C_{bl} \cdot V^2 = (8 \text{ columns} \cdot \frac{1024 \text{ cells}}{1 \text{ column}} \cdot \frac{0.12 \mu m}{1 \text{ cell}} \cdot \frac{0.25 \text{ fF}}{1 \mu m}) (0.9 \text{ V})^2 = 159 \text{ fJ}$ (all bitlines discharge)
 Now say we have 256 rows, 32 columns. What E_{wl} ?
 $E_{wl} = C_{wl} \cdot V^2 = (32 \text{ cells} \cdot \frac{0.5 \mu m}{1 \text{ cell}} \cdot \frac{0.25 \text{ fF}}{1 \mu m}) (0.9 \text{ V})^2 = 2.5 \text{ fJ}$
 & E_{bl} ?
 $E_{bl} = (32 \text{ cols} \cdot \frac{256 \text{ cells}}{1 \text{ col}} \cdot \frac{0.12 \mu m}{1 \text{ cell}} \cdot \frac{0.25 \text{ fF}}{1 \mu m}) (0.9 \text{ V})^2 = 159 \text{ fJ}$

SRAM

byte-addressable memory; 64 words of storage. 1:1 aspect ratio.
 memory capacity in bits: $64 \times 64 = 4096 = 4 \text{ K bits}$
 rows, cols = $\sqrt{4096} = 64$
 mem capacity in bytes: $64 \times 8 = 512 \text{ B}$
 number of address bits: $\log_2(512) = 9 \text{ bits}$

column decode bits:
 each row has 64 columns = 64b = 8B
 $\log_2(8) = 3$ column decode bits
 # row decode bits = # address bits - column decode bits
 $= 9 - 3 = 6$

CSA array multiplier
 critical path (for 8x8 array with 7 bit ripple-carry adder)
 $= t_{\text{partial-product}} + 8 t_{\text{FA}} + 7 t_{\text{FA}}$

Caches

direct mapped cache. 8KB size, 64B blocks. memory addresses 32 bits
 offset bits: $64 \text{ B blocks} = 2^6 \text{ bytes}$
 $\rightarrow 6 \text{ offset bits}$
 index bits: $\$ \text{ size} = 8 \text{ KB} = 2^{13} \text{ B}$
 $\rightarrow 13 - 6 = 7 \text{ index bits}$
 tag bits: $32 - 6 - 7 = 19 \text{ tag bits}$